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FDMA510PZ

## June 2014

# Single P-Channel PowerTrench<sup>®</sup> MOSFET -20V, -7.8A, $30m\Omega$

#### **Features**

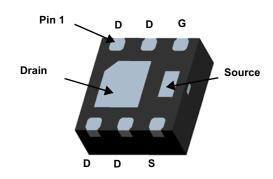
- Max  $r_{DS(on)}$  = 30m $\Omega$  at  $V_{GS}$  = -4.5V,  $I_D$  = -7.8A
- Max  $r_{DS(on)}$  = 37m $\Omega$  at  $V_{GS}$  = -2.5V,  $I_D$  = -6.6A
- Max  $r_{DS(on)}$  = 50m $\Omega$  at  $V_{GS}$  = -1.8V,  $I_D$  = -5.5A
- Max  $r_{DS(on)}$  = 90m $\Omega$  at  $V_{GS}$  = -1.5V,  $I_D$  = -2.0A
- Low profile 0.8mm maximum in the new package MicroFET 2X2 mm
- HBM ESD protection level > 3KV typical (Note 3)
- Free from halogenated compounds and antimony oxides
- RoHS Compliant



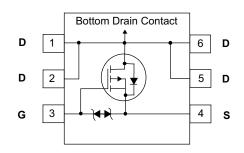
## **General Description**

This device is designed specifically for battery charge or load switching in cellular handset and other ultraportable applications. It features a MOSFET with low on-state resistance.

The MicroFET 2X2 package offers exceptional thermal performance for its physical size and is well suited to linear mode applications.



MicroFET 2X2 (Bottom View)



# MOSFET Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage		-20	V
V <sub>GS</sub>	Gate to Source Voltage		±8	V
	Drain Current -Continuous	(Note 1a)	-7.8	_
ID	-Pulsed		-24	A
D	Power Dissipation	(Note 1a)	2.4	W
$P_{D}$	Power Dissipation	(Note 1b)	0.9	] vv
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	52	°C/W
$R_{\theta,IA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	145	C/VV

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
510	FDMA510PZ	MicroFET 2X2	7"	8mm	3000units

# **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted

Parameter

Off Char	Off Characteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = –250μA, referenced to 25°C		-13		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -16V, V_{GS} = 0V$			-1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$			±10	μΑ

**Test Conditions** 

Тур

Max

Units

### On Characteristics

Symbol

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-0.4	-0.7	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = –250μA, referenced to 25°C		3		mV/°C
		$V_{GS} = -4.5V$ , $I_D = -7.8A$		27	30	
		$V_{GS} = -2.5V$ , $I_D = -6.6A$		34	37	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = -1.8V$ , $I_D = -5.5A$		46	50	mΩ
		$V_{GS} = -1.5V$ , $I_D = -2.0A$		60	90	
		$V_{GS} = -4.5V$ , $I_D = -7.8A$ , $T_J = 125$ °C		36	40	
9 <sub>FS</sub>	Forward Transconductance	$V_{DD} = -5V, I_D = -7.8A$		26		S

# **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	\\ - 40\\ \\ - 0\\	1110	1480	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1MHz	205	275	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 11/11/12	185	280	pF

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	.,	7	14	ns
t <sub>r</sub>	Rise Time	$V_{DD} = -10V, I_{D} = -7.8A$ $V_{GS} = -4.5V, R_{GEN} = 6\Omega$	9	18	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = -4.5V, K <sub>GEN</sub> = 012	125	200	ns
t <sub>f</sub>	Fall Time		64	103	ns
$Q_g$	Total Gate Charge	., 5,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	19	27	nC
Q <sub>gs</sub>	Gate to Source Charge	$V_{DD} = -5V, I_{D} = -7.8A$ $V_{GS} = -4.5V$	2.1		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	v <sub>GS</sub> <del>-</del>	4.2		nC

# **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				-2	Α
$V_{SD}$	Source to Drain Diode Forward Voltage V <sub>GS</sub> = 0V, I <sub>S</sub> = -2A			-0.8	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$I_{\rm F} = -7.8$ A, di/dt = 100A/µs		66	106	ns
Q <sub>rr</sub>	Reverse Recovery Charge	1F = -7.8A, di/dt = 100A/μs		44	71	nC

#### Notes:

<sup>1.</sup> R<sub>0,1A</sub> is determined with the device mounted on a 1 in 2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0,1C</sub> is guaranteed by design while R<sub>0,CA</sub> is determined by the user's board design.



a. 52°C/W when mounted on a 1 in² pad of 2 oz copper.



b. 145°C/W when mounted on a minimum pad of 2 oz copper.

<sup>2.</sup> Pulse Test: Pulse Width < 300µs, Duty cycle < 2.0%.
3. The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

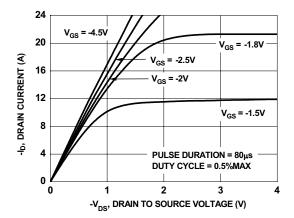


Figure 1. On-Region Characteristics

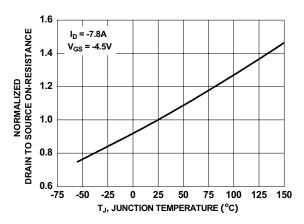


Figure 3. Normalized On-Resistance vs Junction Temperature

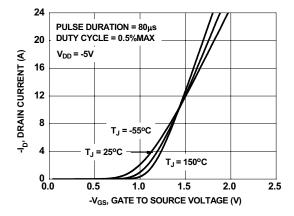


Figure 5. Transfer Characteristics

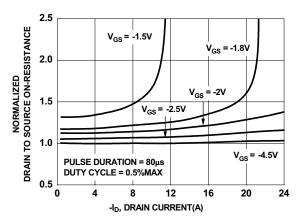


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

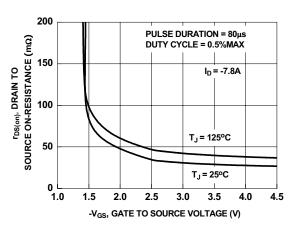


Figure 4. On-Resistance vs Gate to Source Voltage

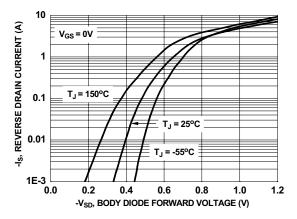


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

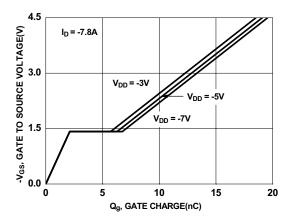


Figure 7. Gate Charge Characteristics

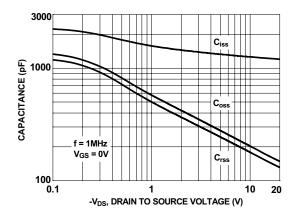


Figure 8. Capacitance vs Drain to Source Voltage

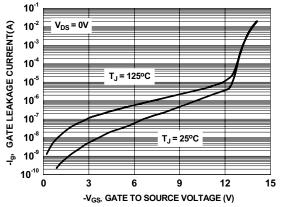


Figure 9. Gate Leakage Current vs Gate to Source Voltage

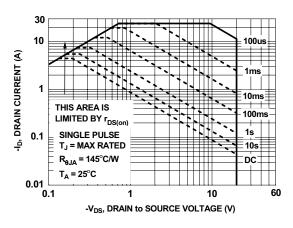


Figure 10. Forward Bias Safe Operating Area

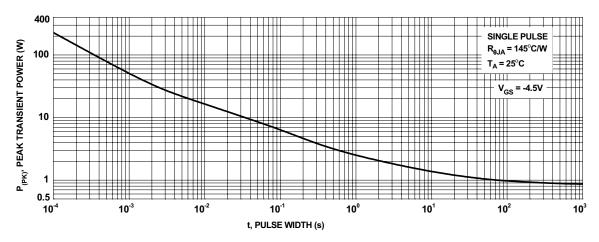


Figure 11. Single Pulse Maximum Power Dissipation

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

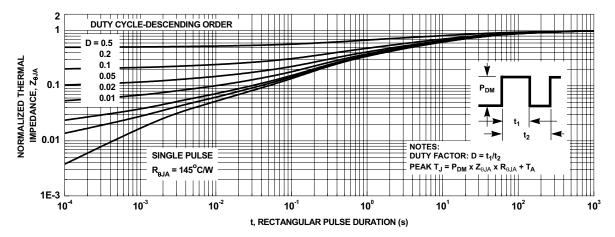
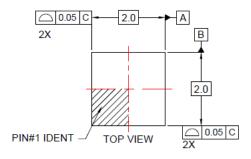
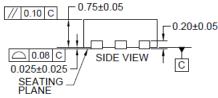
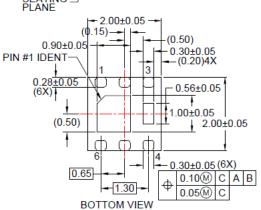


Figure 12. Transient Thermal Response Curve

# **Dimensional Outline and Pad Layout**

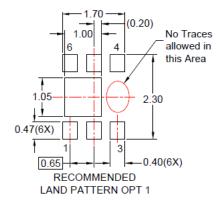


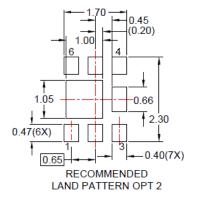




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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP06Lrev4.







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